



## Material Content Data Sheet



Sales Product Name	BBY 53-02V H6327			Issued		16. January 2020		
MA#	MA001379676							
Package	PG-SC79-2-1			Weight*		1.67 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		18	
	noble metal	gold	7440-57-5	0.003	0.18		1788	
	inorganic material	silicon	7440-21-3	0.026	1.53	1.71	15275	17081
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92	
	non noble metal	titanium	7440-32-6	0.001	0.05		460	
	non noble metal	chromium	7440-47-3	0.002	0.14		1380	
	non noble metal	copper	7440-50-8	0.767	45.83	46.03	458271	460203
wire	non noble metal	copper	7440-50-8	0.005	0.30	0.30	3047	3047
encapsulation	organic material	carbon black	1333-86-4	0.007	0.43		4343	
	plastics	epoxy resin	-	0.124	7.38		73838	
	inorganic material	silicondioxide	60676-86-0	0.596	35.62	43.43	356162	434343
leadfinish	non noble metal	tin	7440-31-5	0.055	3.26	3.26	32598	32598
plating	noble metal	silver	7440-22-4	0.088	5.27	5.27	52728	52728
*deviation	< 10%	Sum in total:			100.00		1000000	

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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